MA4X713 (MA713)

Silicon epitaxial planar type

For switching

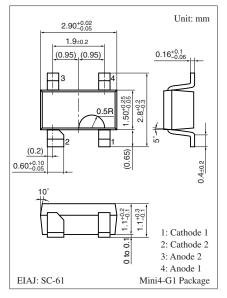
For wave detection

Features

- Two isolated elements are contained in one package, allowing high-density mounting
- Two MA3X704A (MA704A) is contained in one package (of a type in the same direction)
- \bullet Forward voltage $V_{\rm F}$, optimum for low voltage rectification
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}

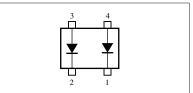
0 "							
Parameter		Symbol	Rating	Unit			
Reverse voltage		V _R	30	V			
Maximum peak reverse voltage		V _{RM}	30	V			
Peak forward	Single	I _{FM}	150	mA			
current	Double *		110				
Forward current	Single	I _F	30	mA			
	Double *		20				
Junction temperature		Tj	125	°C			
Storage temperature		T _{stg}	-55 to +125	°C			
Note) *: Value of each diode in double diodes used							

Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol: M1N

Internal Connection



Note) *: Value of each diode in double diodes used.

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _{F1}	$I_F = 1 \text{ mA}$			0.4	V
	V _{F2}	$I_F = 30 \text{ mA}$			1.0	
Reverse current	I _R	$V_R = 30 V$			1	μΑ
Terminal capacitance	Ct	$V_R = 1 V, f = 1 MHz$		1.5		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 10 \text{ mA}$		1.0		ns
		$I_{rr} = 1 \text{ mA}, R_L = 100 \Omega$				
Detection efficiency	η	$V_{in} = 3 V_{(peak)}$, f = 30 MHz		65		%
		$R_L = 3.9 \text{ k}\Omega, C_L = 10 \text{ pF}$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

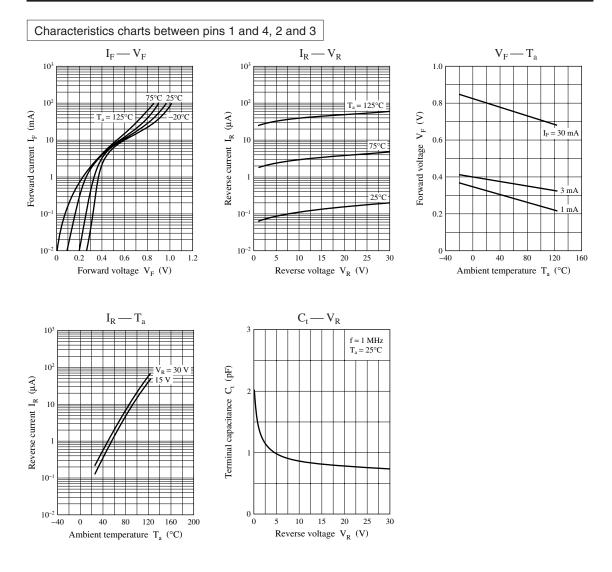
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

4. *: trr measurement circuit

3. Absolute frequency of input and output is 2 GHz.

Bias Application Unit (N-50BU) Input Pulse Output Pulse V_R V_R V_R

Panasonic



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